RF Noise Simulation for Submicron MOSFET's Based on Hydrodynamic Model

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Outline

- Motivation
- Simulation Method
- Validity Examination
- Drift-Diffusion Model vs. Hydrodynamic Model
- Simulation Results for 0.25 μ m nMOSFET
- Conclusions



Motivation (RF CMOS)

- Rapid f_t increase of MOSFETs, driven by the microprocessor industry, attracts RF designers.
- Promise of integrating whole systems on a single chip.
- Noise behavior in short channel MOSFETs is not well understood yet.



Motivation (Continue) (MOSFET Noise)

- Flicker (1/f) Noise
 - ♦ Dominant up to few MHz range
 - Significant in mixer circuits (Up-conversion Error)

Shot Noise

- ♦ Dominant in the subthreshold region
- Thermal Noise (Velocity Fluctuation Noise)
 - ♦ Dominant in high frequencies



Motivation (*Continue*) (HF MOSFET Noise - Thermal)

- Excess drain noise in short channel MOSFETs caused by carrier heating near drain junction.
 - A. A. Abidi (IEEE TED, 1986)
 - B. Wang et al. (IEEE JSSC, 1994)
- Induced gate noise due to the distributed nature of MOS devices.
 - Introduced by A. van der Ziel in 1976
 - NO QUANTITATIVE report to date
 - D. K. Shaeffer et al. (IEEE JSSC, 1997)



Simulation Method

(1D vs. 2D/3D)

- 1D Approach
 - Using transmission line analogy
 - Reasonable comutational cost
 - Poor accuracy
- 2D/3D Approach
 - Impedance Field Method + Adjoint analysis
 - Better accuracy, incorporating 2nd order effects
 - Expensive in implementation and simulation (no HD to date)



Simulation Method (*Continue*) (Hybrid Approach)







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Validity Check - I (First-Order Network Parameters)





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Validity Check - II (Continue) (Segmentation Error for Uniform Transmission Line)



 $\Delta x L/\lambda = 10^{-5} \mu m$ corresponds to 280GHz for $L=0.25 \mu m$ divided into 20 segments



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Validity Check - III (Long Channel MOSFET Case)



Classical Values

$\gamma = 1.0$	(Linear)
= 2/3	(Saturation)
$\delta = 4/3$	(Saturation)
c = j0.395	(Saturation)

$$\gamma = \frac{\overline{i_d^2}}{4 \, k \, T \, \Delta f \, g_{d0}}$$
$$\delta = \frac{\overline{i_g^2}}{4 \, k \, T \, \Delta f \, \Re[Y_{GS}]}$$
$$c = \frac{\overline{i_g i_d^*}}{\sqrt{\overline{i_g^2} \, \overline{i_d^2}}}$$



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Comparison to Measured Data

 $(\gamma - \delta - c \text{ vs. } F_{min} - R_n - Y_{opt})$

- Intrinsic
 - ♦ Drain Noise
 - ♦ Gate Noise
 - ♦ Correlation
- Extrinsic
 - ♦ Interlayer Capacitance
 - ♦ Gate Resistance
- Parasitic
 - ♦ Pad Loss
 - ♦ Routing Inductance



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$$F_{min} = 1 + 2R_n(G_{opt} + G_c)$$

$$\approx 1 + 2R_nG_{opt}$$

$$R_n = |B|^2 \frac{\overline{i_d^2}}{4 \, k \, T \, \Delta f}$$

$$G_{opt} = \sqrt{\frac{G_u}{R_n} + G_c^2} \approx \sqrt{\frac{G_u}{R_n}}$$

$$B_{opt} = -B_c$$

$$Y_c = \frac{D}{B} - \frac{c}{B} \sqrt{\frac{\overline{i_g^2}}{\overline{i_d^2}}} \approx \frac{D}{B}$$

$$G_u = (1 - |c|^2) \frac{\overline{i_g^2}}{4 \, k \, T \, \Delta f}$$

$$B = \frac{1}{\frac{Y_{21} + Y_{22}}{Y_{21} + Y_{22}}}$$

$$D = \frac{Y_{11} + Y_{12}}{Y_{21} + Y_{22}} + 1$$









Conclusions

- Accurate and efficient noise simulation technique : 1D active transmission line + 2D device simulation
- First known attempt to use an advanced (HD) transport model for 2D noise analysis
- First successful noise simulation results for deep submicron MOSFETs

